

SMD CERAMIC ANTENNA

Data Sheet

KH-3216-G-31-L

For 1175&1570MHz

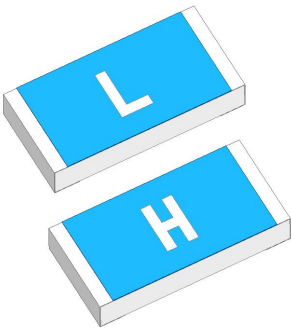
3.2x1.6mm [EIA1206]

Feature

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain
- Operating Temp. : -40°C~+85°C

Application

- GPS&BD&GLONASS

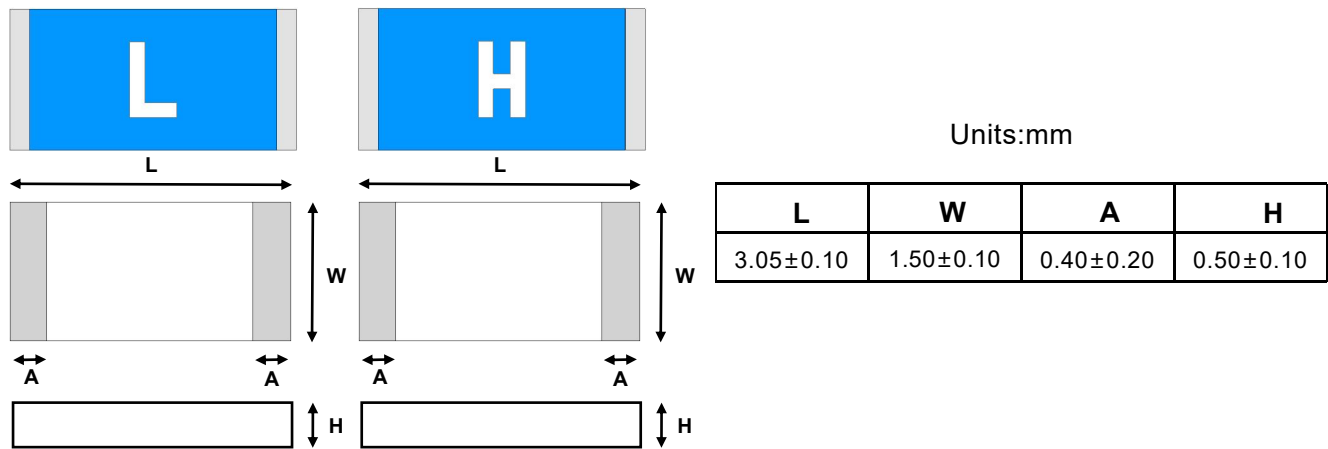


Electrical Characteristics per line(TA=25°C)

Parameter	Specification		Units
Frequency Band	1160~1280	1560~1600	MHz
Polarization	Linear		
*Peak Gain	2.8	2.1	dBi
*Peak Efficiency	72%	65%	%
Impedance	50		Ω

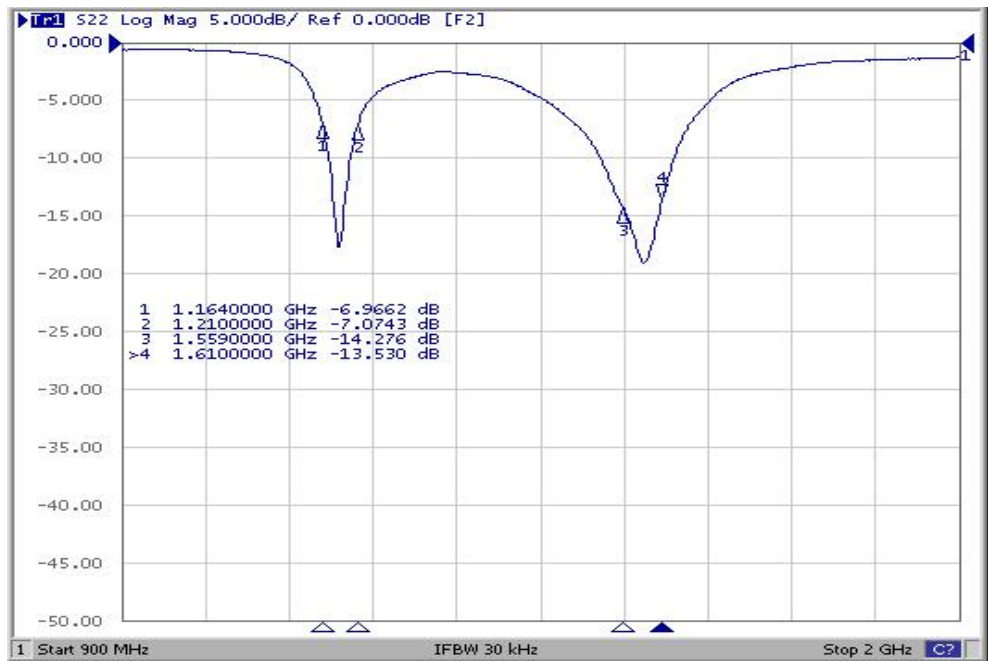
Test condition: Test board size 80*60 mm;
Matching circuit: Pi matching circuit will be required.

Product Dimension



Typical Characteristics

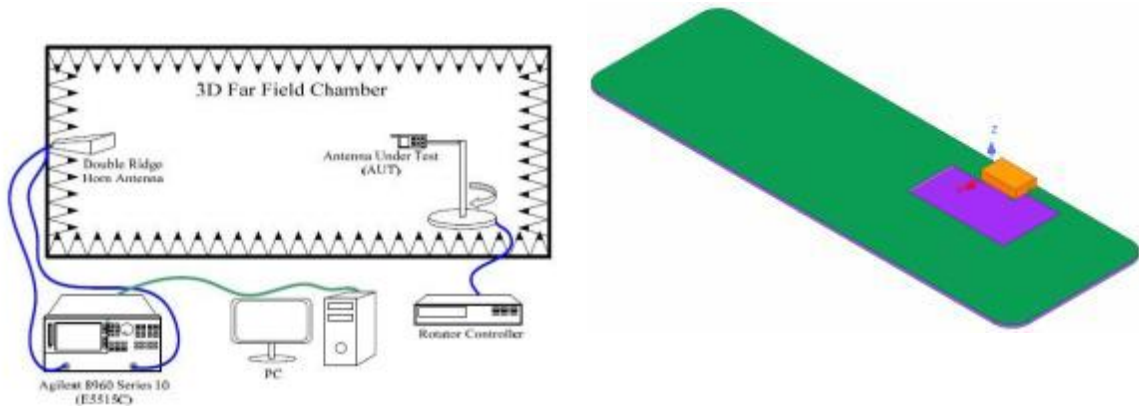
Fig. 1 Return Loss



Radiation Pattern

The Gain pattern is measured in FAR -field chamber. DUT is placed on the table of rotator , a standard horn antenna and Vector Network Analyzer is used to collect data.

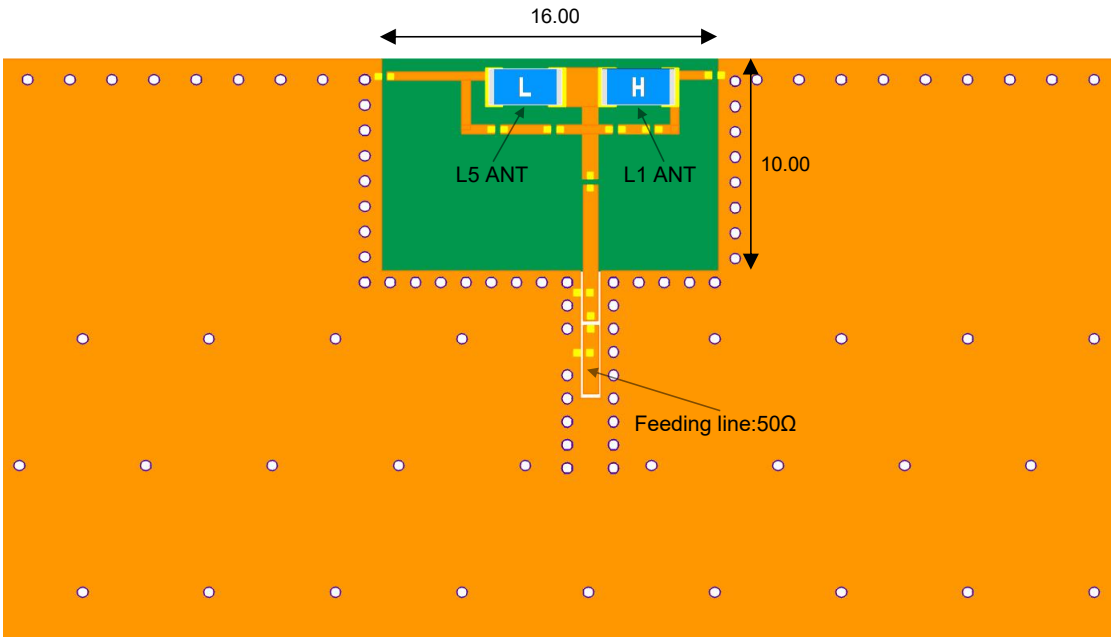
Fig.2 FAR-field Chamber



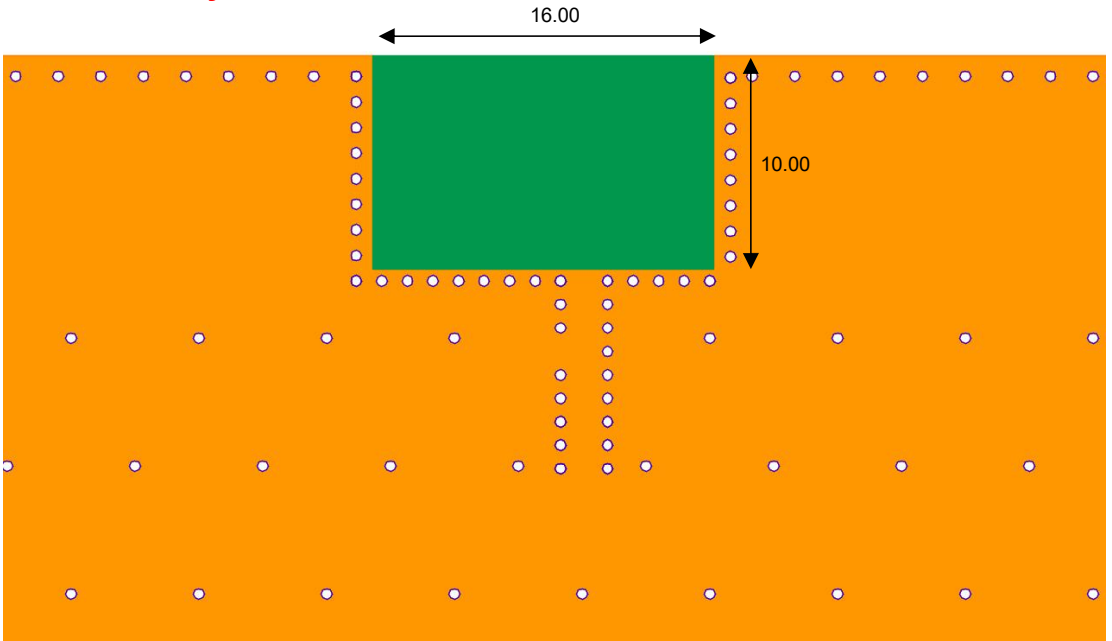
Recommend PCB Layout

Test condition: Test board size 80*60 mm;

Top Layer(unit mm)



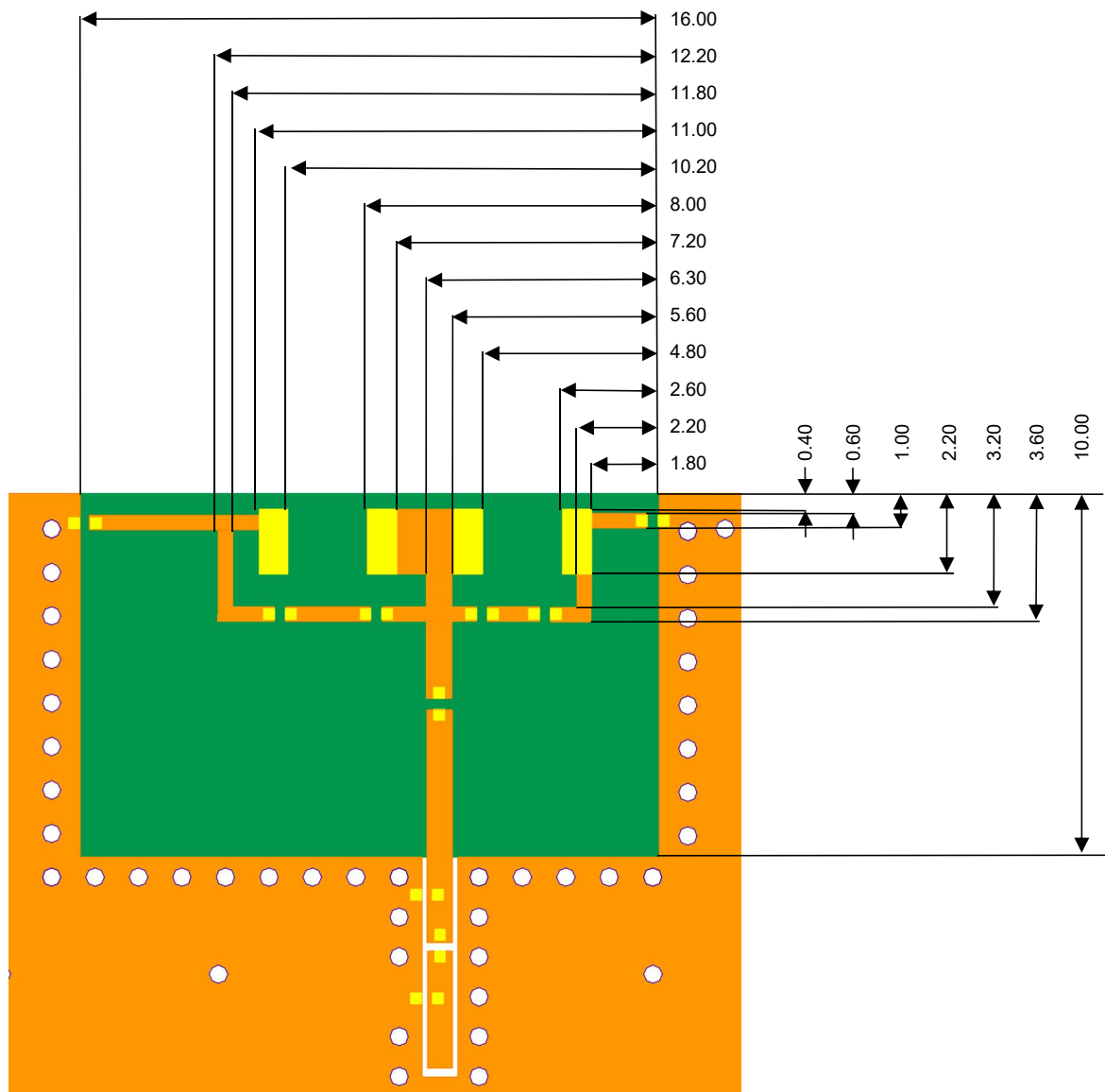
Bottom Layer (unit mm)



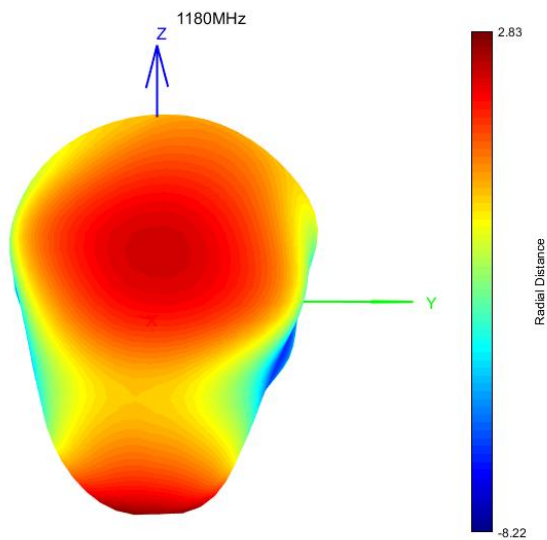
Recommend PCB Layout

Test condition: Test board size 80*60 mm;

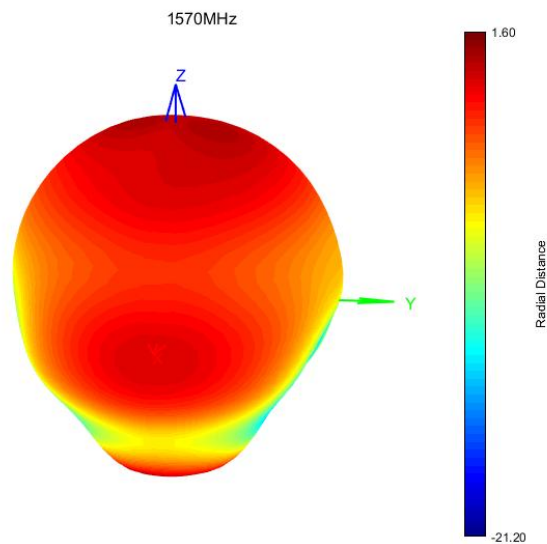
Top Layer (unit mm)



3D Gain Pattern (1180 MHz)

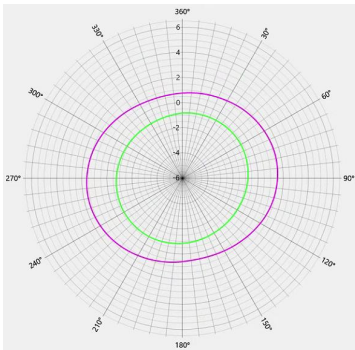


3D Gain Pattern (1570 MHz)

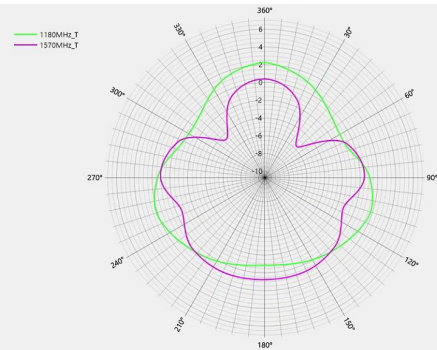


2D Gain Pattern (1180MHz/1570MHz)

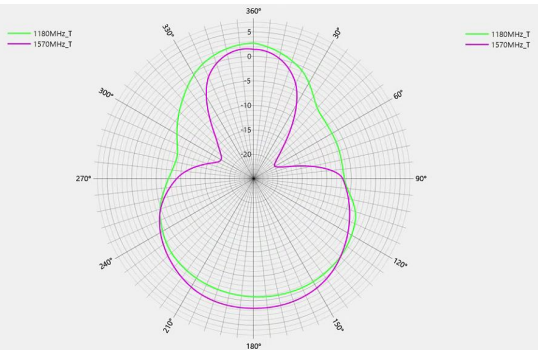
Theta 90



Pin 0

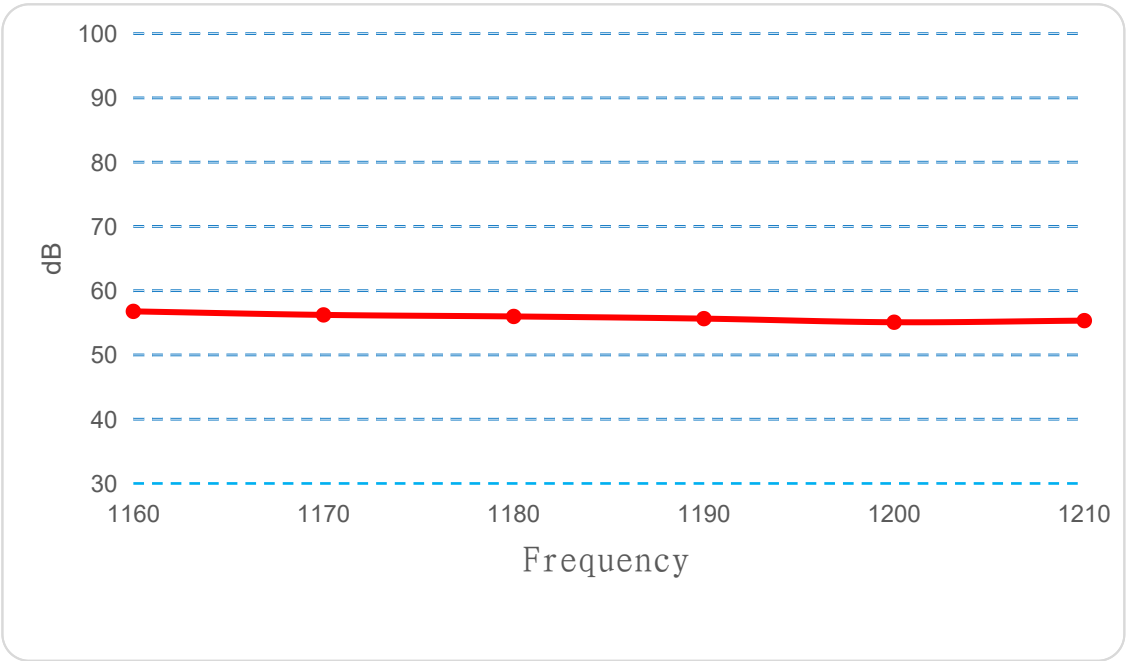


Pin 90

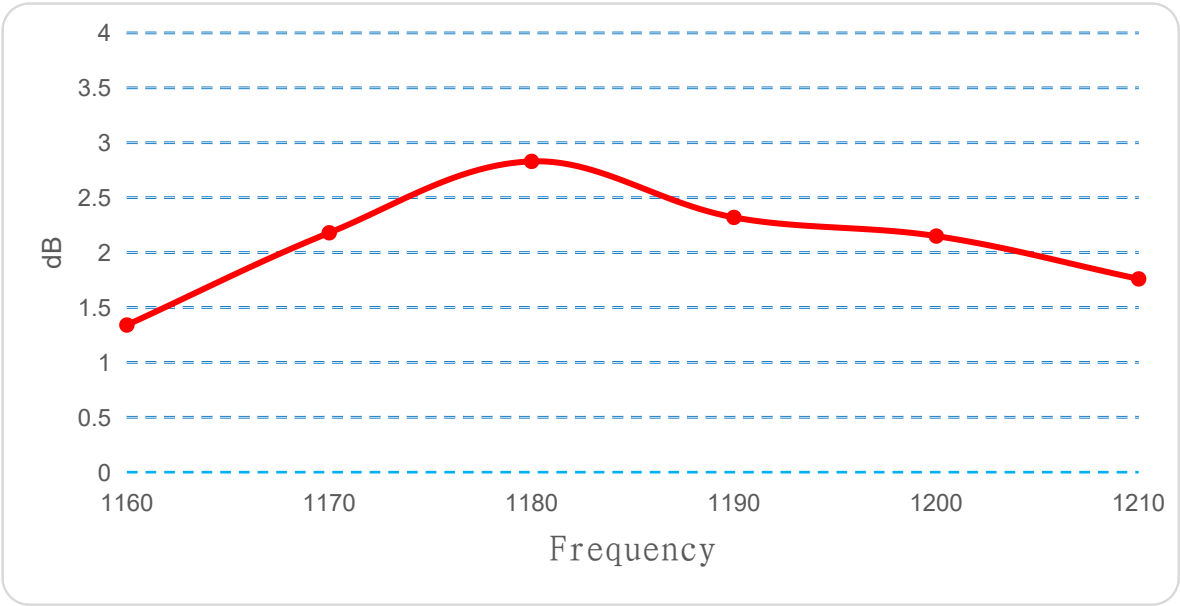


Efficiency&Gain

Efficiency

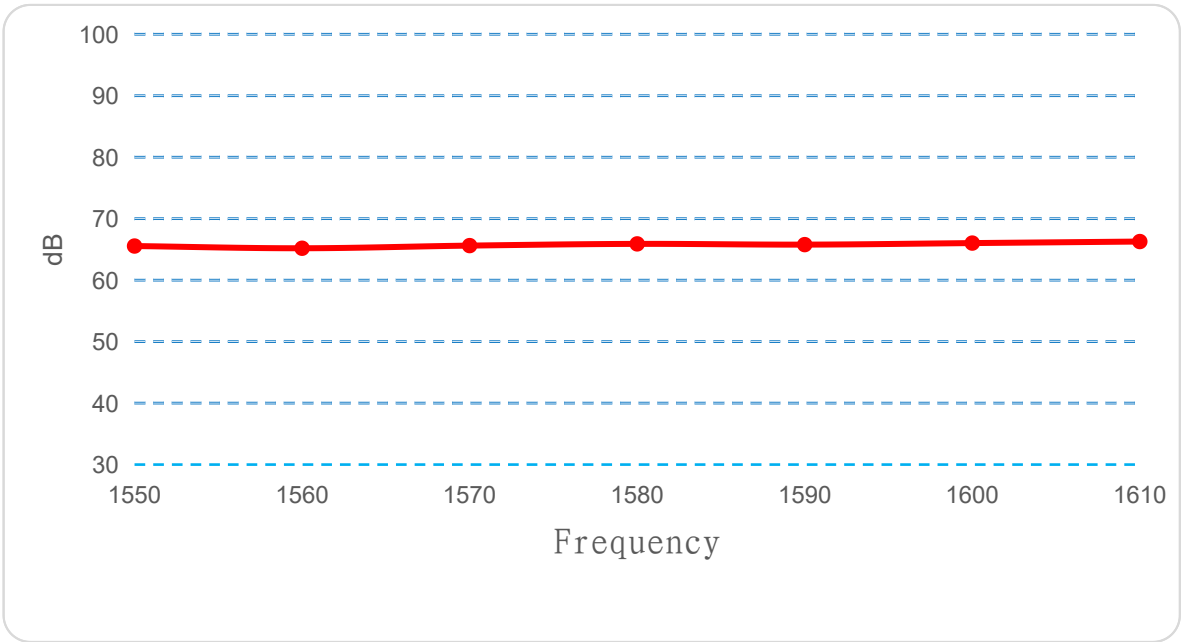


Gain

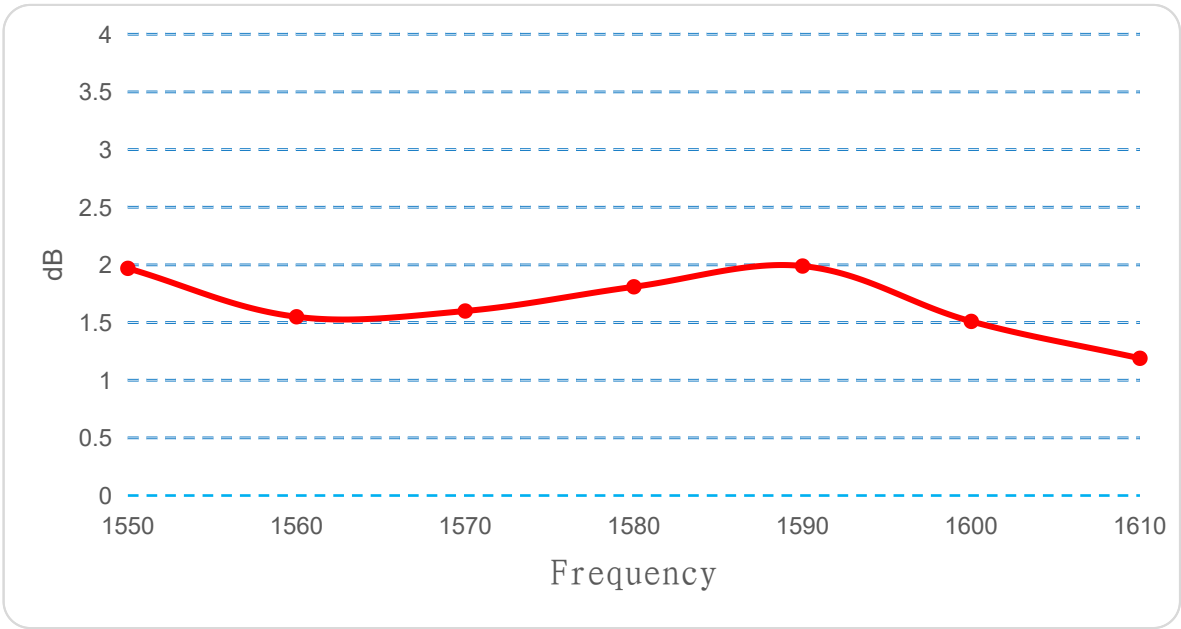


Efficiency&Gain

Efficiency



Gain



Item	Condition	Specification
Thermal shock	1. 30±3 minutes at -40°C±5°C, 2. Convert to +105°C (5 minutes) 3. 30±3 minutes at +105°C±5°C, 4. Convert to -40°C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: 85±5°C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	No apparent damage Fulfill the electrical spec. after test.	1. Temperature: 150°C±5°C 2. Time: 1000 hours.
Low temperature resistance	1. Temperature: -40°C±5°C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5°C 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245±5°C for 3±1 seconds.	No apparent damage

(2) Storage Condition

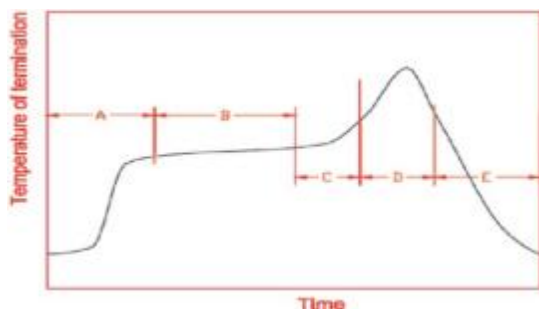
(a)At warehouse: The temperature should be within 0 ~ 30°C and humidity should be less than 60% RH.The product should be used within 1 year from the time of elivery.

(b)On board: The temperature should be within -40 ~ 85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to +85°C.

Recommended Reflow Solder curve



A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
E	Regular cooling	if 260°C	20s~40s
		200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C

A	B	C	D	E	F	L	W
8.00±0.3	3.50± 0.05	1.75±0.1	2.00±0.05	4.00±0.1	1.50±0.1	2.30± 0.1	1.55± 0.1

Order Information

Device	Package	Net Weight	Carrier	Quantity	HSF Status
KH-3216-G-31-L	3216	0.0089g	Tape&Reel	5000pcs	RoHS compliant

Revision history

Date	Revision	Description of changes
2026-03-05	1.0	First Version